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- Output Ports Have Equivalent 25-Ω Series Resistors, So No External Resistors Are Required
- State-of-the-Art *EPIC-*II*B*[™] BiCMOS Design Significantly Reduces Power Dissipation
- Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Plastic (N) and Ceramic (J) DIPs, and Ceramic Flat (W) Package

description

These octal buffers and line drivers are designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters. Together with the 'ABT2241 and 'ABT2244A, these devices provide combinations of inverting and noninverting outputs, symmetrical active-low output-enable (OE) inputs, and complementary OE and OE inputs. These devices feature high fan-out and improved fan-in.

SN54ABT2240 . . . J OR W PACKAGE SN74ABT2240A . . . DB, DW, N, OR PW PACKAGE (TOP VIEW)

	•	'	
10E [1A1 [2Y4 [1A2 [2Y3 [1A3 [2Y2 [1A4 [2Y1 [GND [4 5 6 7	19 18 17 16 15 14 13	V _{CC} 2OE 1Y1 2A4 1Y2 2A3 1Y3 2A2 1Y4 2A1

SN54ABT2240 . . . FK PACKAGE (TOP VIEW)

	2Υ4 1A1 1 <u>OE</u> 2 <u>OE</u>	
		1
1A2 2Y3 1A3 2Y2 1A4	3 2 1 20 19 4 18	1Y1
2Y3	4 18 5 17 6 16 7 15	2A4
1A3	6 16	1Y2
2Y2	7 15	2A3
1A4	8 14	1Y3
	<u>9 10 11 12 13</u>	
		J
	2Y1 GND 2A1 1Y4 2A2	

These devices are organized as two 4-bit line drivers with separate \overline{OE} inputs. When \overline{OE} is low, the devices pass inverted data from the A inputs to the Y outputs. When \overline{OE} is high, the outputs are in the high-impedance state.

The outputs, which are designed to sink up to 12 mA, include equivalent 25- Ω series resistors to reduce overshoot and undershoot.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT2240 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT2240A is characterized for operation from –40°C to 85°C.



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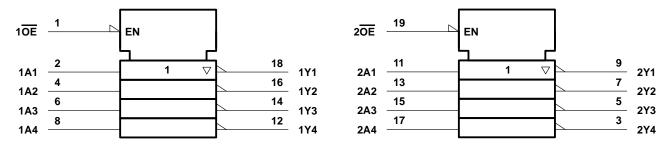


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FUNCTION TABLE (each buffer)								
INPUTS OUTPUT								
OE	Α	Y						
L	Н	L						
L	L	Н						
Н	Х	Z						

logic symbol[†]



9 2Y1

7 2Y2

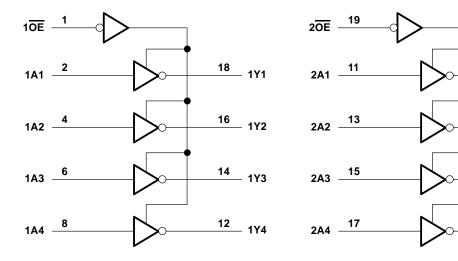
3 2Y4

2Y3

5

[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

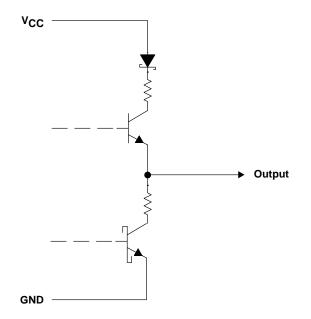
logic diagram (positive logic)





SN54ABT2240, SN74ABT2240A OCTAL BUFFERS AND LINE/MOS DRIVERS WITH 3-STATE OUTPUTS SCBS232D – JANUARY 1991 – REVISED MAY 1997

schematic of Y outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V _{CC} Input voltage range, V _I (see Note 1) Voltage range applied to any output in the high		
Current into any output in the low state, IO		
Input clamp current, IIK (VI < 0)		
Output clamp current, I_{OK} (V _O < 0)		
Package thermal impedance, θ_{JA} (see Note 2)	: DB package	115°C/W
	DW package	
	N package	
	PW package	128°C/W
Storage temperature range, T _{stg}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.



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recommended operating conditions (see Note 3)

				SN54ABT2240		2240A	UNIT
			MIN	MAX	MIN	MAX	
V _{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	VIH High-level input voltage		2		2		V
VIL	Low-level input voltage	w-level input voltage		0.8		0.8	V
VI	VI Input voltage		0	VCC	0	VCC	V
ЮН	High-level output current			-24	4 –32 mA		mA
IOL	OL Low-level output current			12		12	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
Т _А	Operating free-air temperature	perature		125	-40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		TEST CONDITIONS		T _A = 25°C			SN54ABT2240		SN74ABT2240A			
PARA	METER	TEST CO	NDITIONS	MIN	TYP [†]	MAX	MIN	MAX	MIN	MAX	UNIT	
VIK		V _{CC} = 4.5 V,	lj = -18 mA			-1.2		-1.2		-1.2	V	
		V _{CC} = 4.5 V,	I _{OH} = -3 mA	2.5			2.5		2.5			
M	$V_{CC} = 5 V,$	I _{OH} = –3 mA	3			3		3		V		
VOH			I _{OH} = -24 mA	2			2				v	
		$V_{CC} = 4.5 V$	I _{OH} = -32 mA	2*					2			
VOL		V _{CC} = 4.5 V,	I _{OL} = 12 mA			0.8		0.8		0.8	V	
V _{hys}					100						mV	
l		V _{CC} = 5.5 V,	$V_I = V_{CC} \text{ or } GND$			±1		±1		±1	μA	
IOZH		V _{CC} = 5.5 V,	V _O = 2.7 V			10*		10		10	μΑ	
IOZL		V _{CC} = 5.5 V,	V _O = 0.5 V			-10*		-10		-10	μΑ	
loff		V _{CC} = 0,	$V_{I} \text{ or } V_{O} \leq 4.5 \text{ V}$			±100				±100	μΑ	
ICEX		V _{CC} = 5.5 V, V _O = 5.5 V	Outputs high			50		50		50	μΑ	
10‡		V _{CC} = 5.5 V,	V _O = 2.5 V	-50	-100	-180	-50	-180	-50	-180	mA	
			Outputs high		1	250		250		250	μA	
ICC		$V_{CC} = 5.5 \text{ V}, I_O = 0,$ $V_I = V_{CC} \text{ or GND}$	Outputs low		24	30		30		30	mA	
			Outputs disabled		0.5	250		250		250	μA	
	Data	V _{CC} = 5.5 V, One input at 3.4 V,	Outputs enabled			1.5		1.5		1.5		
∆ICC§	inputs	Other inputs at V _{CC} or GND	Outputs disabled			0.05		0.05		0.05	mA	
	Control inputs	V_{CC} = 5.5 V, One input Other inputs at V_{CC} or				1.5		1.5		1.5		
Ci		V _I = 2.5 V or 0.5 V			4						pF	
Co		V _O = 2.5 V or 0.5 V			7						pF	

* On products compliant to MIL-PRF-38535, this parameter does not apply.

[†] All typical values are at $V_{CC} = 5 V$.

* Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.



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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

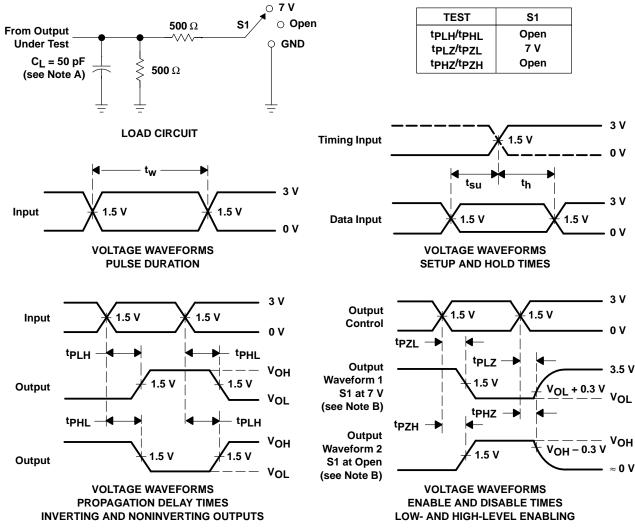
			SN54ABT2240					
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			MIN N	МАХ	UNIT
			MIN	TYP	MAX			
tPLH	A	A Y	1	3	4	1	5	ns
^t PHL			3	4.8	5.8	3	6.3	115
^t PZH	OE	V	1.5	3.7	4.7	1.5	6.1	ns
^t PZL	OE	I	4.2	6.5	7.6	4.2	8.8	115
^t PHZ	OE	×	1.9	3.8	5.6	1.9	6.2	ns
^t PLZ	UE	1	2.5	4.7	5.8	2.5	6.9	115

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

			SN74ABT2240A					
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			MIN N	МАХ	UNIT
			MIN	TYP	MAX			
^t PLH	A	v	1	3	4.1	1	4.8	ns
^t PHL			2.1	4.1	5.1	2.1	5.4	115
^t PZH		V	1.1	3.1	4.7	1.1	5.2	ns
^t PZL	OE	T	1.7	4.5	6.4	1.7	6.8	115
^t PHZ	OE	v	1.8	3.4	5.7	1.8	6.4	ns
^t PLZ	UE	I	1.9	3.6	6	1.9	6.2	115



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PARAMETER MEASUREMENT INFORMATION

NOTES: A. CL includes probe and jig capacitance.

B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns.

D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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